

Title (en)

REPAIR PATCH, REPAIR PATCH MOLDING METHOD, AND REPAIR METHOD FOR COMPOSITE MATERIAL

Title (de)

REPARATURPFLASTER, REPARATURPFLASTERFORMVERFAHREN UND REPARATURVERFAHREN FÜR VERBUNDMATERIAL

Title (fr)

TIMBRE DE RÉPARATION, PROCÉDÉ DE MOULAGE DE TIMBRE DE RÉPARATION ET PROCÉDÉ DE RÉPARATION POUR MATÉRIAU COMPOSITE

Publication

**EP 3831585 B1 20240911 (EN)**

Application

**EP 19858816 A 20190723**

Priority

- JP 2018169850 A 20180911
- JP 2019028830 W 20190723

Abstract (en)

[origin: EP3831585A1] Provided is a repair patch 10 for a composite material to repair a part 5 to be repaired which is a repair target of the composite material, the patch including: a patch main body 11 that is formed by laminating a plurality of prepregs P in a thickness direction, and has a bonding surface 18 to be bonded to the part 5 to be repaired; and a removal layer 12 that is provided on the bonding surface 18 and is peelable off from the patch main body 11. The bonding surface 18 includes a side surface 13 that is inclined with respect to the thickness direction of the patch main body 11. The removal layer 12 includes a plurality of slits 17 that cause the removal layer 12 to have a shape complementary to a shape of the side surface 13 of the patch main body 11.

IPC 8 full level

**B29C 73/10** (2006.01); **B29C 70/30** (2006.01); **B29C 70/54** (2006.01)

CPC (source: EP US)

**B29C 70/30** (2013.01 - EP US); **B29C 70/542** (2013.01 - EP US); **B29C 73/10** (2013.01 - EP US); **B29C 73/14** (2013.01 - US); **B29C 2793/0036** (2013.01 - EP); **B32B 17/04** (2013.01 - US); **B32B 2260/023** (2013.01 - US); **B32B 2556/00** (2013.01 - US); **B64F 5/40** (2017.01 - US); **Y10T 428/14** (2015.01 - US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 3831585 A1 20210609**; **EP 3831585 A4 20210929**; **EP 3831585 B1 20240911**; JP 2020040303 A 20200319; JP 7018855 B2 20220214; US 11396141 B2 20220726; US 2021252805 A1 20210819; WO 2020054220 A1 20200319

DOCDB simple family (application)

**EP 19858816 A 20190723**; JP 2018169850 A 20180911; JP 2019028830 W 20190723; US 201917275081 A 20190723